

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
7 October 2004 (07.10.2004)

PCT

(10) International Publication Number
WO 2004/085521 A1

(51) International Patent Classification⁷: **C08J 5/08**

(21) International Application Number:
PCT/FI2004/000177

(22) International Filing Date: 26 March 2004 (26.03.2004)

(25) Filing Language: Finnish

(26) Publication Language: English

(30) Priority Data:
20030466 28 March 2003 (28.03.2003) FI

(71) Applicant (for all designated States except US): **BAKE-
LITE OY** [FI/FI]; Teollisuustie 20 B, FI-82430_Puhos
(FI).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **RAINIO,**
Jouni [FI/FI]; c/o Bakelite Oy, Teollisuustie 20 B,
FI-82430_Puhos (FI).

(74) Agent: **PAPULA OY**; P. O. Box 981, FI-00101_Helsinki
(FI).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), Euro-
pean (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR,
GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.

(54) Title: **ADHESIVE COMPOSITION**

(57) Abstract: An adhesive composition for use in the manufacture of wood-based boards, said adhesive composition containing resin and a foaming agent, and said composition being foamable. According to the invention, the adhesive composition contains 40 - 80 w-% resin, 5 - 30 w-% filler, 0 - 40 w-% solvent, and 0.1 - 10 w-% foaming agent, which has been selected from organic and/or inorganic surface-active sulfate, sulfonate, phosphate or phosphonate compounds or their derivatives or mixtures.

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